

Contents

Preface	xv
Chapter 1 Introduction	1
1.1 Causes of EMI	1
1.2 Electrical Transmission	2
1.3 EMI Effects	4
1.4 EMC Practices	5
1.5 Growth of the EMC Field	6
1.6 Organization of the Book	7
Chapter 2 Sources of Conducted Interference and its Characteristics	9
2.1 Nature of Sources of Conducted Interference	9
2.1.1 Nonfunctional Sources	10
2.1.2 Functional Sources	13
2.1.3 The Conducted Spectrum	14
2.2 Characteristics of Interference	14
2.2.1 Bandwidth	15
2.2.2 Amplitude Behavior	18
2.2.3 Waveform	19
2.2.4 Occurrence	19
2.3 Design Practice for Minimizing Interference	22
2.3.1 Noise Source Treatment	22
2.3.2 Noise Transmission Considerations	23
2.3.3 Sensitive Device Treatment	24
References	24
Chapter 3 Sources of Radiated Interference and its Characteristics	25
3.1 Sources of Radiated Interference	25
3.1.1 Nonfunctional Sources	33
3.1.2 Functional Sources	39
3.1.3 The Radiated Spectrum	41
3.1.4 Example of a Radiated Spectrum Situation	43

3.2	Electromagnetic Pulse (EMP)	47
3.2.1	EMP Effects	49
3.2.2	EMP Circuit Susceptibility Analysis	50
3.2.3	Protection Against EMP	53
3.2.4	Combined Environmental Effects	55
3.2.5	System-Generated EMP (SGEMP)	55
3.3	Possible Future Interference Sources	55
3.4	Design Practice	56
3.4.1	Noise Source Treatment	56
3.4.2	Noise Transmission	57
3.4.3	Sensitive Devices	57
	References	57
	Chapter 4 Interference Coupling by Conduction and Radiation	59
4.1	Coupling via Conducted Paths	62
4.1.1	Radiative Transfer	63
4.1.2	Inductive Transfer	64
4.1.3	Capacitive Transfer	66
4.2	Radiation Coupling	67
4.3	Design Practice	72
4.3.1	Interference Coupling within Circuits	72
4.3.2	Conversion: Wire-Field-Wire	72
4.3.3	Isolation through Shielding	72
4.3.4	Effect of Circuit Impedance on Radiation	72
	References	74
	Chapter 5 Grounding and Bonding	75
5.1	The Design Process	75
5.2	Definitions of Grounding and Bonding	76
5.3	Fundamental Grounding Concepts	77
5.4	Circuit Grounding Considerations	83
5.5	Power Supply Grounding	87
5.6	Relay Grounding	90
5.7	Cable Shield Grounding	90
5.8	Facility Grounds	94
5.9	Earth Grounds	95
5.9.1	Vertical Rods	97
5.9.2	Horizontal Grounds	98
5.9.3	Plates	99
5.9.4	Incidental Electrodes	99
5.10	Ground Resistance Measurement	100
5.10.1	Triangulation	100
5.10.2	Ratio Method	101
5.10.3	Fall of Potential Method	101
5.10.4	Earth Resistivity and its Measurement	103

5.11	Grounding Design Guidelines	105
5.11.1	Fundamental Concepts	105
5.11.2	Safety Considerations	106
5.11.3	Circuit Grounding	106
5.11.4	Cable Shielding	106
5.12	Bond Purposes and Types	107
5.13	Bonding Methods	108
5.14	Surface Treatment	109
5.15	Corrosion and Alloying	109
5.16	Bonding Effectiveness	114
5.17	Bonding Resistance	115
5.18	Bonding Impedance	117
5.19	Bonding Tests	119
5.20	General Guidelines for Good Bonds	122
	References	122
	Chapter 6 Shielding	125
6.1	The Shielding Effectiveness of Solid Materials	125
6.1.1	Absorption	126
6.1.2	Reflection	127
6.1.3	Internal Reflection	128
6.1.4	Magnetic Shielding	129
6.2	Multiple Solid Shields	131
6.3	Thin-Film Shielding	132
6.4	Shield Seams	134
6.5	Nonsolid Shielding	135
6.5.1	Analysis of Screened Apertures	136
6.5.2	Woven Material Performance	139
6.5.3	Honeycomb Shielding Materials	141
6.5.4	Panel Opening Shielding	142
6.6	Cable and Connector Shielding	147
6.6.1	Cable Shielding	148
6.6.2	Surface Transfer Impedance	149
6.6.3	Shield Terminations	151
6.6.4	Connector Shielding	152
6.7	Summary of Good Shielding Practice	158
6.7.1	General	160
	References	161
	Chapter 7 Barrier Shields	163
7.1	Wave Diffraction	163
	References	169
	Chapter 8 Filtering	171
8.1	Filter Characteristics	171
8.1.1	Frequency Characteristics	172

8.1.2	Impedance Levels	172
8.1.3	Voltage Rating	172
8.1.4	Current Rating	172
8.1.5	Insulation Resistance	173
8.1.6	Size and Weight	173
8.1.7	Temperature	173
8.1.8	Reliability	173
8.2	Filter Design	173
8.2.1	Reflective Filters	174
8.2.2	Lossy Filters	177
8.2.3	Component Behavior	180
8.3	Transient Suppression	182
8.4	Power-Line Filters	184
8.5	Noise Reduction Circuits	186
8.5.1	Noise Blankers	186
8.5.2	Noise Cancelers	187
8.5.3	Noise Limiters	187
8.6	Special Filter Components	188
8.6.1	Feed-Through and Three-Terminal Capacitors	188
8.6.2	Beads	190
8.7	Special Filter Types	191
8.7.1	Transmitter Filters	191
8.7.2	Receiver Preselector Filters	191
8.7.3	Receiver IF Filters	194
	References	195
	Chapter 9 Materials and Special Devices	197
9.1	Gaskets	197
9.2	Fingers	202
9.3	Conductive Coatings	205
9.3.1	The Need for Conductive Coatings	205
9.3.2	Methods for Applying Coatings	205
9.3.3	Types of Coatings	207
9.3.4	Coating Thickness	208
9.3.5	Conductive Plastics	208
9.3.6	Shielding Effectiveness of Conductive Coatings	209
9.4	Filter Contact Connectors	209
	References	214
	Chapter 10 Equipment Design	215
10.1	Transmitters	215
10.1.1	General Considerations	215
10.1.2	Signal-Generating Circuits	216
10.1.3	Interstage Circuits	216
10.1.4	Output Stages	216

10.1.5	Transmitter Cases	217
10.1.6	Antenna Circuits	217
10.2	Receivers	217
10.2.1	Antenna-to-Antenna Coupling	218
10.2.2	Anomalous Detection	218
10.3	Antenna Systems	219
10.4	Power Supplies	219
10.4.1	Source-Induced Noise	219
10.4.2	Load-Induced Noise	219
10.5	Motors	220
10.6	Control Devices	220
10.6.1	Relays	220
10.6.2	Contacts	220
10.6.3	Solid-State Switches	221
10.7	Digital Circuits	221
10.7.1	A/D and D/A Converters	221
10.7.2	Diodes, Transistors, and Microcircuits	222
10.8	Digital Computers	222
10.8.1	Susceptibility Causes	222
10.8.2	Computer Power	223
10.9	Integrated Circuit Susceptibility	226
10.9.1	Susceptibility Levels	226
10.9.2	Minimizing Integrated Circuit Susceptibility Problems	236
	References	236
	Chapter 11 Mathematical Models	237
11.1	Source Models	239
11.2	Coupling Models	240
11.3	Susceptor Models	242
11.4	Example of Model Development	243
11.4.1	Capacitive Coupling	243
11.4.2	Inductive Coupling	244
11.5	Summary	246
	References	247
	Chapter 12 Intrasystem and Intersystem Analysis Programs	249
12.1	Intrasystem Programs	252
12.1.1	SEMCAP	252
12.1.2	Interference Prediction Process One (IPP-1)	262
12.1.3	Intrasystem Electromagnetic Compatibility Analysis Program (IEMCAP)	272
12.1.4	Intrasystem Analysis Program (IAP)	275
12.1.5	Other Intrasystem Programs	278
12.2	Intersystem Programs	278
12.2.1	Transmitter and Receiver Gain	281

12.2.2	Propagation Path Loss	281
12.2.3	Off-Frequency Rejection	283
12.3	Program Selection	283
	References	285
	Chapter 13 EMI Prediction	287
13.1	Computer Analysis Philosophy	288
13.2	Using the Models for Compatibility Analysis	289
13.3	Using the Models for Specification Development	290
13.3.1	Interference	293
13.3.2	Susceptibility Limits	295
13.4	Using the Models for Waiver Evaluation	296
13.5	The Use and Insertion of Test Data	297
13.6	Program Outline Example	297
	Chapter 14 Military Standards and Specifications	299
14.1	Philosophy of Standards and Specifications	299
14.2	Military EMC Standards	302
14.2.1	Standards Dealing with the Use of EMC Control Methods	302
14.2.2	Standards Dealing with Component and System Performance	302
14.3	Units in which Limits are Expressed	307
14.4	Definitions and Terminology	308
	References	311
	Chapter 15 Industrial and Government Specifications	313
15.1	Organizations Promulgating EMC Standards	313
15.1.1	Industrial Organizations	313
15.1.2	US Government Organizations	314
15.1.3	Organizations Outside the US	314
15.2	FCC Requirements	314
15.3	European EMC Requirements	315
15.4	NCMDRH Requirements	316
15.5	SAE Standards	316
15.6	CISPR Recommendations	318
	References	321
	Chapter 16 EMC Test Plans and Procedures	323
16.1	Establishing the Test Environment	324
16.2	Interface Considerations	324
16.3	Test Plan Contents	324
16.4	Compatibility Criteria	325
16.5	Test Automation	326
16.6	Preparation for the Test	326
16.6.1	Test Schedules	326

16.6.2	Preparation of System and Laboratory	327
16.6.3	Selection of Monitoring Points	327
16.6.4	Selection of Instrumentation	327
16.6.5	Data Analysis	328
16.6.6	Test Reporting	328
16.6.7	Other Test Factors	328
16.7	Test Procedures	329
Chapter 17	Measurement Methods for Field Strength and for Conducted Interference	331
17.1	Bandwidth and Receiver Sensitivity	331
17.2	Swept Frequency Measurements	333
17.3	Field Strength Measurements	334
17.3.1	Antenna Proximity Effects	334
17.3.2	Power Flux Density Close to an Antenna	334
17.4	Time <i>versus</i> Frequency Domain Measurements	336
	References	337
Chapter 18	Test Equipment	339
18.1	Conducted Measurements	339
18.1.1	The 10 μ F Capacitor	339
18.1.2	The Line Impedance Stabilization Network (LISN)	339
18.1.3	Voltage Probes	340
18.1.4	Current Probes	341
18.1.5	The Surface Current Probe	341
18.2	Radiated Measurements	343
18.2.1	Antennas	343
18.2.2	Parallel Striplines	343
18.2.3	The Crawford Cell	345
18.3	Sources	346
18.3.1	Impulse Generators	347
18.3.2	Spike Generators	347
18.3.3	Sweep Oscillators	348
18.3.4	Power Oscillators and Amplifiers	348
18.4	Receivers	348
18.5	Automatic EMI Measuring Systems	350
18.6	Fiber Optics	350
	References	352
Chapter 19	Test Facilities	353
19.1	Shielded Enclosures	353
19.1.1	Internal Reflections	354
19.2	Absorbers	355
19.3	Open Field Test Sites	356
	References	359

Chapter 20 Testing Computing Devices to FCC and VDE	
Requirements	361
20.1 Devices Subject to Test	361
20.2 Requirements	362
20.3 Measurement Methods	362
20.3.1 Test Conditions	364
20.3.2 Conducted Power-Line Measurements	367
20.3.3 Radiated Emission Measurements	369
References	371
Appendices	373
A International System of Units (SI)	373
B Frequency Band Nomenclature	375
Index	377